



**FOR IMMEDIATE RELEASE**

**CONTACT:**

Abby Tsoi  
President of SMTA China  
+852-2515-1268  
Fax: +852-2515-1175  
Email: abbytsoi@kasion.com



**SMTA China Presents Awards at SMTA China East 2010 Conference/Nepcon China 2010**

**April 2010** — SMTA China announces that it presented awards for the 10 best papers/presentations and two best exhibits at the SMTA China East 2010 Conference Award Presentation Ceremony, held on Wednesday, April 21, 2010 at the Shanghai Everbright International Hotel in conjunction with the SMTA China Annual Breakfast Reception.

**Integrated Service Technology Inc.'s** Jeffrey Lee was awarded The Best Paper of Technology Conference One for the paper titled "Sn Whisker Concern in IC Packaging for High Reliability Applications."

**Shenzhen Kaifa Technology Co., Ltd.'s** Dr. Caiying He was awarded The Best Paper of Technology Conference Two for the presentation titled "Thermo-Mechanical Simulation and Optimization Analysis for Warpage-Induced PBGA Solder Joint Failures."

**Motorola (China) Electronic Ltd.'s** Davy Liu was awarded The Outstanding Paper of Technology Conference One for the paper titled "Studies of Component Discoloration in Lead-Free Process."

**DfR Solutions's** Dr. Randy Kong was awarded The Outstanding Paper of Technology Conference Two for the paper titled "The Reliability Challenges of QFN Packaging."

Henley Zhou, from **Flextronics Industrial (Zhuhai) Co., Ltd.**, received the award for The Best Presentation of Technology Conference One for the presentation titled "Package on Package (PoP) Assembly Process Development for 0.4 mm x 0.5 mm Pitch BGA."

Dr. Caiying He, from **Shenzhen Kaifa Technology Co., Ltd.**, received the award for The Best Presentation of Technology Conference Two for the presentation titled "Thermo-Mechanical Simulation and Optimization Analysis for Warpage-Induced PBGA Solder Joint Failures."

Phil Zhang, from **Kyzen**, received the award for The Best Presentation of Vendor Conference One for the presentation titled "Flux Residue and Its Impact on Reliability."

Nobe Yan, from **Shenzhen Kunqi Xinhua Technology Co., Ltd.**, received the award for The Best Presentation of Vendor Conference One for the presentation titled "Green Solution for Tin Slag."

Paul Wood, from **OK International**, received the award for The Best Presentation of Vendor Conference Two for the presentation titled "Minimizing Micro-cracks in Solar Cell

Interconnection during Manual Soldering.”

Fei Liu, from **Dongguan Anda Automation Equipment Company Ltd.**, received the award for The Best Presentation of Vendor Conference Three for the presentation titled “Energy Saving and Emission Reduction in Wave Soldering.”

**CyberOptics Corporation** received the award for The Best Emerging Exhibit of the Year 2010 China East with the product of “Automatic Optical Inspection (AOI) System, model QX500™.”

**Test Research, Inc.**, received the award for The Best Exhibit Technology of the Year 2010 China East with the product of “3D Solder Paste Inspection System, model TR7007.”

For more information about the SMTA China, contact Ms. Peggy Chen at +86-21-5609-3010; fax: +86-21-5609-3020; E-mail: [peggy@smta.org](mailto:peggy@smta.org).



Best Paper/Presentation Awards,  
Best Exhibit Awards Presented by  
SMTA China during the SMTA China  
East 2010 Conference.